HIGH-SPEED 2.5V 512/256K x 18 ASYNCHRONOUS DUAL-PORT STATIC RAM WITH 3.3V OR 2.5V INTERFACE

Features

- True Dual-Port memory cells which allow simultaneous access of the same memory location
- High-speed access
 - Commercial: 10/12/15ns (max.)

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- Industrial: 10/12ns (max.)
- RapidWrite Mode simplifies high-speed consecutive write cycles
- Dual chip enables allow for depth expansion without external logic
- IDT70T633/1 easily expands data bus width to 36 bits or more using the Master/Slave select when cascading more than one device
- M/S = VIH for BUSY output flag on Master, $M/\overline{S} = VIL$ for \overline{BUSY} input on Slave
- **Busy and Interrupt Flags**
- On-chip port arbitration logic
- Functional Block Diagram

- Full hardware support of semaphore signaling between ports on-chip
- Fully asynchronous operation from either port
- Separate byte controls for multiplexed bus and bus matching compatibility
- Sleep Mode Inputs on both ports
- ٠ Supports JTAG features compliant to IEEE 1149.1 in BGA-208 and BGA-256 packages
- ٠ Single 2.5V (±100mV) power supply for core
- LVTTL-compatible, selectable 3.3V (±150mV)/2.5V (±100mV) power supply for I/Os and control signals on each port
- Available in a 256-ball Ball Grid Array and 208-ball fine pitch **Ball Grid Arrav**
- Industrial temperature range (-40°C to +85°C) is available ٠ for selected speeds
- Green parts available, see ordering information



- BUSY and INT are non-tri-state totem-pole outputs (push-pull). 3
- The sleep mode pin shuts off all dynamic inputs, except JTAG inputs, when asserted. OPTx, INTx, M/S and the sleep mode pins themselves (ZZx) are not affected during sleep mode.

AUGUST 2019

NOTES:

2.

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

Description

The IDT70T633/1 is a high-speed 512/256K x 18 Asynchronous Dual-Port Static RAM. The IDT70T633/1 is designed to be used as a stand-alone 9216/4608K-bit Dual-Port RAM or as a combination MAS-TER/SLAVE Dual-Port RAM for 36-bit-or-more word system. Using the IDT MASTER/SLAVE Dual-Port RAM approach in 36-bit or wider memory system applications results in full-speed, error-free operation without the need for additional discrete logic.

This device provides two independent ports with separate control, address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in memory. An automatic power down

feature controlled by the chip enables (either \overline{CE} or CE1) permit the on-chip circuitry of each port to enter a very low standby power mode.

The IDT70T633/1 has a RapidWrite Mode which allows the designer to perform back-to-back write operations without pulsing the R/\overline{W} input each cycle. This is especially significant at the 10ns cycle times of the IDT70T633/1, easing design considerations at these high performance levels.

The 70T633/1 can support an operating voltage of either 3.3V or 2.5V on one or both ports, controlled by the OPT pins. The power supply for the core of the device (VDD) remains at 2.5V.

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Pin Configuration^(1,2,3)

70T633/1 BC256^(5,6) BCG256^(5,6)

256-Pin BGA

Top View

A1	^{A2}	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12	A13	A14	A15	A16
NC	TDI	NC	A17L	A14L	A11L	A8L	NC	CE1L	OEL	INTL	A 5L	A 2L	A0L	NC	NC
^{B1}	B2	^{B3}	B4	B5	B6	B7	^{B8}	B9	^{B10}	B11	B12	B13	^{B14}	B15	B16
NC	NC	TDO	A18L ⁽⁴⁾	A15L	A12L	A9L	UBl	CE0L	R/WL	NC	A4L	A1L	NC	NC	NC
C1	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11	C12	C13	C14	C15	C16
NC	I/O9L	Vss	A16L	A13L	A10L	A7L	NC	TBL	SEML	BUSYL	A6L	A3L	OPT∟	NC	I/O8L
D1	d2	D3	d4	d5	d6	d7	d8	d9	d10	d11	d12	D13	D14	D15	d16
NC	I/O9r	NC	Vdd	Vddql	Vddql	Vddqr	Vddqr	Vddql	Vddql	Vddqr	Vddqr	Vdd	NC	NC	I/O8r
e1	e2	E3	e4	e5	e6	^{E7}	^{E8}	^{E9}	E10	e11	e12	e13	E14	e15	e16
I/O10r	I/O10l	NC	Vddql	Vdd	Vdd	Vss	Vss	Vss	Vss	Vdd	Vdd	Vddqr	NC	I/O7l	I/O7r
f1	F2	f3	f4	f5	F6	F7	F8	^{F9}	F10	F11	F12	f13	f14	F15	F16
I/O11L	NC	I/O11r	Vddql	Vdd	NC	Vss	Vss	Vss	Vss	Vss	Vdd	Vddqr	I/O6r	NC	I/O6l
G1	G2	g3	g4	G5	G6	_{G7}	_{G8}	G9	G10	G11	G12	g13	g14	G15	G16
NC	NC	I/O12L	Vddqr	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddql	I/O5l	NC	NC
H1	h2	H3	h4	H5	H6	^{H7}	H8	H9	H10	H11	H12	h13	^{H14}	H15	h16
NC	I/O12r	NC	Vddqr	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddql	NC	NC	I/O5r
J1	J2	j3	j4	J5	J6	_{J7}	_{J8}	^{J9}	J10	J11	J12	j13	J14	j15	J16
I/O13L	I/O14R	I/O13R	Vddql	ZZR	Vss	Vss	Vss	Vss	Vss	Vss	ZZL	Vddqr	I/O4r	I/O3r	I/O4L
K1	K2	кз	k4	K5	K6	к7	ка	к9	K10	K11	K12	k13	K14	K15	к16
NC	NC	I/O14L	Vddql	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vss	Vddqr	NC	NC	I/Oзl
l1	L2	l3	l4	l5	L6	L7	L8	L9	L10	L11	l12	l13	l14	L15	l16
I/O15L	NC	I/O15R	Vddqr	Vdd	NC	Vss	Vss	Vss	Vss	Vss	Vdd	Vddql	I/O2l	NC	I/O2r
M1	m2	^{мз}	^{m4}	^{M5}	M6	M7	^{M8}	M9	M10	M11	M12	m13	^{M14}	м15	M16
I/O16R	I/O16L	NC	Vddqr	Vdd	Vdd	Vss	Vss	Vss	Vss	Vdd	Vdd	Vddql	I/O1r	I/O1L	NC
N1	n2	N3	N4	n5	ⁿ⁶	n7	n8	^{N9}	n10	n11	n12	N13	N14	n15	N16
NC	I/O17r	NC	Vdd	Vddqr	Vddqr	Vddql	Vddql	Vddqr	Vddqr	Vddql	Vddql	Vdd	NC	I/Oor	NC
P1	p2	P3	P4	P5	P6	P7	P8	P9	^{P10}	^{p11}	P12	P13	P14	P15	P16
NC	I/O17L	TMS	A16R	A13R	A10R	A7R	NC	TBR	SEMr	BUSYr	A6R	A 3R	NC	NC	I/Ool
^{R1}	R2	^{R3}	R4	R5	R6	R7	r8	R9	r10	^{R11}	R12	R13	^{R14}	^{R15}	R16
NC	NC	TRST	A18R ⁽⁴⁾	A15R	A12R	A9R	UBr	CE0R	R/Wr	M/S	A 4R	A 1R	OPTr	NC	NC
T1	T2	T3	T4	T5	т6	t7	T8	^{T9}	T10	t11	T12	T13	T14	^{T15}	^{T16}
NC	TCK	NC	A17R	A 14R	А11R	A 8R	NC	CE1R	OEr	INTr	A 5R	A 2R	A 0R	NC	NC

5670 drw 02c

- 1. All VDD pins must be connected to 2.5V power supply.
- 2. All VDDD pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to VDD (2.5V), and 2.5V if OPT pin for that port is set to Vss (0V).
- 3. All Vss pins must be connected to ground supply.
- 4. A18x is a NC for IDT70T631.
- 5. Package body is approximately 17mm x 17mm x 1.4mm, with 1.0mm ball-pitch.
- 6. This package code is used to reference the package diagram.

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

PinConfigurations^(1,2,3)(con't.)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
А	I/O9L	NC	Vss	TDO	NC	A16L	A12L	ABL	NC	Vdd	SEML	ĪNTL	A4L	Aol	OPT∟	NC	Vss	А
В	NC	Vss	NC	TDI	A17L	A13L	A9L	NC	CEOL	Vss	BUSYL	A5L	A1L	Vss	VDDQR	I/O8L	NC	В
С	VDDQL	I/O9R	VDDQR	Vdd	A18L ⁽⁴⁾	A14L	A10L	ŪBL	CE1L	Vss	R/WL	A6L	A2L	VDD	I/O8R	NC	Vss	С
D	NC	Vss	I/O10L	NC	A15L	A11L	A7L	ĹΒL	VDD	ŌĒL	NC	A3L	Vdd	NC	VDDQL	I/O7L	I/O7R	D
Е	I/O11L	NC	Vddqr	I/O10R										I/O6L	NC	Vss	NC	Е
F	VDDQL	I/O11R	NC	Vss										Vss	I/O6R	NC	VDDQR	F
G	NC	Vss	I/O12L	NC		70T633/1								NC	Vddql	I/O5L	NC	G
н	VDD	NC	VDDQR	I/O12R		BF208 ^(5,6)							VDD	NC	Vss	I/O5r	Н	
J	VDDQL	VDD	Vss	ZZR		BFG208 ^(5,6)								ZZL	Vdd	Vss	VDDQR	J
К	I/O14R	Vss	I/O13R	Vss					-Ball p Vie		1			I/O3r	VDDQL	I/O4r	Vss	K
L	NC	I/O14L	Vddqr	I/O13L										NC	I/O3L	Vss	I/O4L	L
М	VDDQL	NC	I/O15R	Vss										Vss	NC	I/O2R	Vddqr	М
Ν	NC	Vss	NC	I/O15L										I/O1R	Vddql	NC	I/O2L	Ν
Ρ	I/O16R	I/O16L	VDDQR	NC	TRST	A16R	A12R	A8R	NC	Vdd	SEMR	ĪNTr	A4R	NC	I/O1L	Vss	NC	Ρ
R	Vss	NC	I/O17R	тск	A17R	A13R	Aar	NC	CEOR	Vss	BUSYR	A5R	A1R	Vss	VDDQL	I/Oor	VDDQR	R
т	NC	I/O17L	VDDQL	TMS	A18R ⁽⁴⁾	A14R	A10R	ŪBR	CE1R	Vss	R/WR	A6R	A2R	Vss	NC	Vss	NC	Т
U	Vss	NC	Vdd	NC	A15R	A11R	A7R	<u>LB</u> R	Vdd	ŌĒR	M/S	Азя	Aor	Vdd	OPTR	NC	I/Ool	U

5670 drw 02b

- 1. All VDD pins must be connected to 2.5V power supply.
- 2. All VDDO pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to VDD (2.5V), and 2.5V if OPT pin for that port is set to Vss (OV).
- 3. All Vss pins must be connected to ground.
- 4. A18x is a NC for IDT70T631.
- 5. Package body is approximately 15mm x 15mm x 1.4mm with 0.8mm ball pitch.
- 6. This package code is used to reference the package diagram.
- 7. This text does not indicate orientation of the actual part-marking.

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Pin Names

Left Port	Right Port	Names					
CE0L, CE1L	CEOR, CE1R	Chip Enables (Input)					
R/WL	R/Wr	Read/Write Enable (Input)					
<u>OE</u> L	ŌĒr	Output Enable (Input)					
Aol - A18L ⁽¹⁾	Aor - A18r ⁽¹⁾	Address (Input)					
I/O0L - I/O17L	I/O0r - I/O17r	Data Input/Output					
SEML	SEMR	Semaphore Enable (Input)					
ĪNTL ĪNTR		Interrupt Flag (Output)					
BUSYL BUSYR		Busy Flag (Output)					
		Upper Byte Select (Input)					
LBL LBR		Lower Byte Select (Input)					
VDDQL	VDDQR	Power (I/O Bus) (3.3V or 2.5V) ⁽²⁾ (Input)					
OPTL	OPTR	Option for selecting VDDax ^(2,3) (Input)					
ZZL	ZZR	Sleep Mode Pin ⁽⁴⁾ (Input)					
	M/S	Master or Slave Select (Input) ⁽⁵⁾					
	Vdd	Power (2.5V) ⁽²⁾ (Input)					
	Vss	Ground (0V) (Input)					
	TDI	Test Data Input					
	TDO	Test Data Output					
	ТСК	Test Logic Clock (10MHz) (Input)					
	TMS	Test Mode Select (Input)					
-	TRST	Reset (Initialize TAP Controller) (Input)					

5670 tbl 01

Industrial and Commercial Temperature Ranges

- 1. Address A18x is a NC for IDT70T631.
- VDD, OPTx, and VDDox must be set to appropriate operating levels prior to applying inputs on I/Ox.
- 3. OPTx selects the operating voltage levels for the I/Os and controls on that port. If OPTx is set to Vbb (2.5V), then that port's I/Os and controls will operate at 3.3V levels and Vbbbx must be supplied at 3.3V. If OPTx is set to Vss (0V), then that port's I/Os and controls will operate at 2.5V levels and Vbbbx must be supplied at 2.5V. The OPT pins are independent of one another—both ports can operate at 3.3V levels, both can operate at 2.5V levels, or either can operate at 3.3V with the other at 2.5V.
- 4. The sleep mode <u>pin</u> shuts off all dynamic inputs, except JTAG inputs, when asserted. OPTx, <u>INTx</u>, M/S and the sleep mode pins themselves (ZZx) are not affected during sleep mode. It is recommended that boundary scan not be operated during sleep mode.
- BUSY is an input as a Slave (M/S=VIL) and an output when it is a Master (M/S=VIH).

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

5670 tbl 02

Truth Table I—Read/Write and Enable Control⁽¹⁾

ŌĒ	SEM		CE1	ŪB	LB	R/W	ZZ	Upper Byte I/O9-17	Lower Byte I/O0-8	MODE
Х	Н	Н	Х	Х	Х	Х	L	High-Z	High-Z	Deselected-Power Down
Х	Н	Х	L	Х	Х	Х	L	High-Z	High-Z	Deselected-Power Down
Х	Н	L	Н	Н	Н	Х	L	High-Z	High-Z	Both Bytes Deselected
Х	Н	L	Н	Н	L	L	L	High-Z	Din	Write to Lower Byte
Х	Н	L	Н	L	Н	L	L	Din	High-Z	Write to Upper Byte
Х	Н	L	Н	L	L	L	L	Din	Din	Write to Both Bytes
L	Н	L	Н	Н	L	Н	L	High-Z	Dout	Read Lower Byte
L	Н	L	Н	L	Н	Н	L	Dout	High-Z	Read Upper Byte
L	Н	L	Н	L	L	Н	L	Dout	Dout	Read Both Bytes
Н	Н	L	Н	L	L	Х	L	High-Z	High-Z	Outputs Disabled
Х	Х	Х	Х	Х	Х	Х	Н	High-Z	High-Z	High-Z Sleep Mode

NOTE:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

Truth Table II - Semaphore Read/Write Control⁽¹⁾

		Inp	uts ⁽¹⁾			Outputs		
CE ⁽²⁾	R/W	ŌĒ	ŪB	LΒ	SEM	I/O1-17	I/O0	Mode
Н	Н	L	L	L	L	DATAOUT	DATAOUT	Read Data in Semaphore Flag ⁽³⁾
Н	↑	Х	Х	L	L	Х	DATAIN	Write VOo into Semaphore Flag
L	Х	Х	Х	Х	L			Not Allowed
NOTEC								5670 tbl 03

NOTES:

1. There are eight semaphore flags written to I/Oo and read from all the I/Os (I/Oo-I/O17). These eight semaphore flags are addressed by Ao-A2.

2. \overline{CE} = L occurs when \overline{CE}_0 = VIL and CE1 = VIH. \overline{CE} = H when \overline{CE}_0 = VIH and/or CE1 = VIL.

3. Each byte is controlled by the respective \overline{UB} and $\overline{LB}.$ To read data \overline{UB} and/or \overline{LB} = VIL.

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Recommended Operating Temperature and Supply Voltage⁽¹⁾

Grade	Ambient Temperature	GND	Vdd					
Commercial	0°C to +70°C	0V	2.5V <u>+</u> 100mV					
Industrial	-40°C to +85°C	0V	2.5V <u>+</u> 100mV					
5670 tbl 04								

NOTE:

1. This is the parameter TA. This is the "instant on" case temperature.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
Vterm (Vdd)	Vod Terminal Voltage with Respect to GND	-0.5 to 3.6	V
Vterm ⁽²⁾ (Vddq)	VDDQ Terminal Voltage with Respect to GND	-0.3 to VDDQ + 0.3	V
V _{TERM} ⁽²⁾ (INPUTS and I/O's)	Input and I/O Terminal Voltage with Respect to GND	-0.3 to VDDQ + 0.3	V
Tbias ⁽³⁾	Temperature Under Bias	-55 to +125	٥C
Тѕтс	Storage Temperature	-65 to +150	٥C
Тл	Junction Temperature	+150	٥C
IOUT(For VDDQ = 3.3V)	DC Output Current	50	mA
IOUT(For VDDQ = 2.5V)	DC Output Current	40	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- This is a steady-state DC parameter that applies after the power supply has reached its nominal operating value. Power sequencing is not necessary; however, the voltage on any Input or I/O pin cannot exceed VDDo during power supply ramp up.
- 3. Ambient Temperature under DC Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾

$(TA = +25^{\circ}C, F = 1.0MHz) TQFP$	ONLY	
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Symbol	Parameter	Conditions ⁽²⁾	Max.	Unit					
Cin	Input Capacitance	VIN = 3dV	8	pF					
Cout ⁽³⁾	Output Capacitance	Vout = 3dV	10.5	pF					
5670 tbl 08									

NOTES:

- These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- 3. COUT also references CI/O.

5670 tbl 07

Recommended DC Operating Conditions with VDDQ at 2.5V

Symbol	Parameter	Min.	Тур.	Мах.	Unit
Vdd	Core Supply Voltage	2.4	2.5	2.6	V
VDDQ	I/O Supply Voltage ⁽³⁾	2.4	2.5	2.6	V
Vss	Ground	0	0	0	V
V⊪	Input High Voltage (Address, Control & Data I/O Inputs) ⁽³⁾	1.7		Vddq + 100mV ⁽²⁾	V
Vін	Input High Voltage - JTAG	1.7		Vdd + 100mV ⁽²⁾	۷
Vін	Input High Voltage - ZZ, OPT, M/S	Vdd - 0.2V		Vdd + 100mV ⁽²⁾	۷
V⊫	Input Low Voltage	-0.3 ⁽¹⁾	_	0.7	V
V⊫	Input Low Voltage - ZZ, OPT, M/S	-0.3 ⁽¹⁾		0.2	V
				5	670 tbl 05

NOTES:

1. VIL (min.) = -1.0V for pulse width less than trc/2 or 5ns, whichever is less.

 VIH (max.) = VDDQ + 1.0V for pulse width less than trc/2 or 5ns, whichever is less.

 To select operation at 2.5V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to Vss (0V), and VDDOX for that port must be supplied as indicated above.

Symbol	Parameter	Min.	Тур.	Max.	Unit
VDD	Core Supply Voltage	2.4	2.5	2.6	V
VDDQ	I/O Supply Voltage ⁽³⁾	3.15	3.3	3.45	V
Vss	Ground	0	0	0	V
Vін	Input High Voltage (Address, Control &Data I/O Inputs) ⁽³⁾	2.0		Vddq + 150mV ⁽²⁾	V
ViH	Input High Voltage - JTAG	1.7		VDD + 100mV ⁽²⁾	V
Vін	Input High Voltage - ZZ, OPT, M/S	Vdd - 0.2V		$V_{DD} + 100 mV^{(2)}$	V
V⊫	Input Low Voltage	-0.3(1)		0.8	V
V⊫	Input Low Voltage - ZZ, OPT, M/S	-0.3 ⁽¹⁾		0.2	V

NOTES:

- 1. VIL (min.) = -1.0V for pulse width less than trc/2 or 5ns, whichever is less.
- 2. VIH (max.) = VDDQ + 1.0V for pulse width less than trc/2 or 5ns, whichever is less.
- To select operation at 3.3V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to VDD (2.5V), and VDDOX for that port must be supplied as indicated above.

Industrial and Commercial Temperature Ranges

Recommended DC Operating Conditions with VDDQ at 3.3V

70T633/1S High-Speed 2.5V 512/256K x 18 Asynchronous Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

5670 tbl 09

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 2.5V ± 100mV)

			70T633/1S		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
LL	Input Leakage Current ⁽¹⁾	VDDQ = Max., VIN = 0V to VDDQ		10	μA
	JTAG & ZZ Input Leakage Current ^(1,2)	$V_{DD} = Max., V_{IN} = 0V to V_{DD}$		<u>+</u> 30	μA
LO	Output Leakage Current ^(1,3)	$\overline{CE}_0 = VIH \text{ or } CE_1 = VIL, VOUT = 0V \text{ to } VDDQ$		10	μA
Vol (3.3V)	Output Low Voltage ⁽¹⁾	Iol = +4mA, Vdda = Min.		0.4	V
Voн (3.3V)	Output High Voltage ⁽¹⁾	Ioh = -4mA, VDDQ = Min.	2.4	_	V
Vol (2.5V)	Output Low Voltage ⁽¹⁾	Iol = +2mA, Vdda = Min.		0.4	V
Voн (2.5V)	Output High Voltage ⁽¹⁾	юн = -2mA, Vddq = Min.	2.0		V

NOTES:

1. VDDQ is selectable (3.3V/2.5V) via OPT pins. Refer to page 5 for details.

2. Applicable only for TMS, TDI and TRST inputs.

3. Outputs tested in tri-state mode.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 2.5V ± 100mV)

					Co	70T633/1S10 Com'l & Ind ⁽⁶⁾		3/1S12 m'l Ind	70T633/1S15 Com'l Only		
Symbol	Parameter	Test Condition	Versi	on	Тур. ⁽⁴⁾	Мах.	Тур. ⁽⁴⁾	Мах.	Тур. ⁽⁴⁾	Max.	Unit
IDD	Dynamic Operating Current (Both	CEL and CER= VIL, Outputs Disabled	COM'L	S	300	405	300	355	225	305	mA
	Ports Active)	$f = fMAX^{(1)}$	IND	S	300	445	300	395			
ISB1 ⁽⁶⁾	Standby Current (Both Ports - TTL	$\overline{CE}L = \overline{CE}R = VIH$ f = fMAX ⁽¹⁾	COM'L	S	90	120	75	105	60	85	mA
	Level Inputs)		IND	S	90	145	75	130			
ISB2 ⁽⁶⁾	Standby Current (One Port - TTL	Œ"A" = VI∟ and Œ"B" = VIH ⁽⁵⁾ Active Port Outputs Disabled,	COM'L	S	200	265	180	230	150	200	mA
Level Inputs)	$f = fMAX^{(1)}$	IND	S	200	290	180	255				
ISB3		Both Ports CEL and CER <u>></u> VDDQ - 0.2V,	COM'L	S	2	10	2	10	2	10	mA
	Level Inputs)	$V\text{IN} \geq V\text{DDQ}$ - 0.2V or VIN \leq 0.2V, f = $0^{(2)}$	IND	S	2	20	2	20			
ISB4 ⁽⁶⁾	Full Standby Current (One Port - CMOS Level Inputs)	$\overline{CE}^{"}A^{"} \leq 0.2V \text{ and}$ $\overline{CE}^{"}B^{"} \geq VDDQ - 0.2V^{(5)},$ $VDV = 0.2V(2EV) + 0.2V(2EV)$	COM'L	S	200	265	180	230	150	200	mA
Level inputs)	$ \begin{array}{l} \text{VIN} \geq \text{VDDQ} \text{ - } 0.2\text{V or } \text{VIN} \leq 0.2\text{V}, \\ \text{Active Port, Outputs Disabled,} \\ \text{f} = \text{fMAX}^{(1)} \end{array} $	IND	S	200	290	180	255				
Izz	Sleep Mode Current (Both Ports - TTL	ZZL = ZZR = VIH f = fMAX ⁽¹⁾	COM'L	S	2	10	2	10	2	10	mA
	(Both Ports - TTL Level Inputs)	$I = INIAX^{\prime}$	IND	S	2	20	2	20			
										56	570 tbl 10

NOTES:

1. At f = fMAX, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of 1/trc, using "AC TEST CONDITIONS".

2. f = 0 means no address or control lines change. Applies only to input at CMOS level standby.

3. VDD = 2.5V, TA = $25^{\circ}C$ for Typ. values, and are not production tested. IDD DC(f=0) = 100mA (Typ).

4. $\overline{CE}x = VIL$ means $\overline{CE}ox = VIL$ and CE1x = VIH

 $\overline{CE}x = VIH$ means $\overline{CE}_{0x} = VIH$ or $CE_{1x} = VIL$

 $\overline{CEx} \le 0.2V$ means $\overline{CEox} \le 0.2V$ and $CE1x \ge VDDOX - 0.2V$

 $\overline{CEx} \ge V DDOX - 0.2V$ means $\overline{CEox} \ge V DDOX - 0.2V$ or CE1x - 0.2V "X" represents "L" for left port or "R" for right port.

5. Isb1, Isb2 and Isb4 will all reach full standby levels (Isb3) on the appropriate port(s) if ZZ_L and /or $ZZ_R = V_{IH}$.

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AC Test Conditions (VDDQ = 3.3V/2.5V)

Input Pulse Levels	GND to 3.0V / GND to 2.5V
Input Rise/Fall Times	2ns Max.
Input Timing Reference Levels	1.5V/1.25V
Output Reference Levels	1.5V/1.25V
Output Load	Figure 1

5670 tbl 11







Figure 3. Typical Output Derating (Lumped Capacitive Load).

Industrial and Commercial Temperature Ranges

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Industrial and Commercial Temperature Ranges

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁴⁾

·		70T633/1S10 Com'l & Ind ⁽⁵⁾		Co	70T633/1S12 Com'l & Ind		70T633/1S15 Com'l Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
READ CYCLE								-	
tRC	Read Cycle Time	10		12	_	15	_	ns	
taa	Address Access Time	_	10		12	_	15	ns	
tace	Chip Enable Access Time ⁽³⁾	—	10		12		15	ns	
t ABE	Byte Enable Access Time ⁽³⁾	-	5		6	_	7	ns	
taoe	Output Enable Access Time	-	5		6	_	7	ns	
toн	Output Hold from Address Change	3	_	3	_	3	_	ns	
tız	Output Low-Z Time Chip Enable and Semaphore ^(1,2)	3	_	3	_	3	_	ns	
tlzob	Output Low-Z Time Output Enable and Byte Enable ^(1,2)	0	_	0	_	0	_	ns	
tHZ	Output High-Z Time ^(1,2)	0	4	0	6	0	8	ns	
tpu	Chip Enable to Power Up Time ⁽²⁾	0		0	_	0	_	ns	
tPD	Chip Disable to Power Down Time ⁽²⁾	-	8	-	8	_	12	ns	
tsop	Semaphore Flag Update Pulse (OE or SEM)		4		6		8	ns	
tsaa	Semaphore Address Access Time	2	10	2	12	2	15	ns	
tsoe	Semaphore Output Enable Access Time	-	5	-	6	_	7	ns	

5670 tbl 12

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage⁽⁴⁾

•		Co	70T633/1S10 Com'l & Ind ⁽⁵⁾		70T633/1S12 Com'l & Ind		70T633/1S15 Com'l Only	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
WRITE CYCLE								
twc	Write Cycle Time	10		12		15		ns
tew	Chip Enable to End-of-Write ⁽³⁾	7		9	_	12		ns
taw	Address Valid to End-of-Write	7		9	_	12		ns
tas	Address Set-up Time ⁽³⁾	0		0	_	0		ns
twp	Write Pulse Width	7		9		12		ns
twr	Write Recovery Time	0		0	_	0		ns
tow	Data Valid to End-of-Write	5		7	_	10		ns
tDH	Data Hold Time	0		0		0		ns
twz	Write Enable to Output in High-Z ^(1,2)	_	4		6		8	ns
tow	Output Active from End-of-Write ^(1,2)	3		3		3		ns
tswrd	SEM Flag Write to Read Time	5		5		5		ns
tsps	SEM Flag Contention Window	5		5		5		ns

5670 tbl 13

NOTES:

1. Transition is measured 0mV from Low or High-impedance voltage with Output Test Load (Figure 1).

2. This parameter is guaranteed by device characterization, but is not production tested.

- 3. To access RAM, \overline{CE} = VIL and \overline{SEM} = VIH. To access semaphore, \overline{CE} = VIH and \overline{SEM} = VIL. Either condition must be valid for the entire tew time. \overline{CE} = VIL when \overline{CE}_0 = VIL and \overline{CE}_1 = VIH when \overline{CE}_0 = VIH and \overline{CE}_0 = VIH an
- 4. These values are valid regardless of the power supply level selected for I/O and control signals (3.3V/2.5V). See page 6 for details.

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Industrial and Commercial Temperature Ranges

Waveform of Read Cycles⁽⁵⁾



NOTES:

- 1. Timing depends on which signal is asserted last, $\overline{\text{OE}}$, $\overline{\text{CE}}$, $\overline{\text{LB}}$ or $\overline{\text{UB}}$.
- 2. Timing depends on which signal is de-asserted first CE, OE, LB or UB.
- 3. tbpD delay is required only in cases where the opposite port is completing a write operation to the same address location. For simultaneous read operations BUSY has no relation to valid output data.
- 4. Start of valid data depends on which timing becomes effective last: taoe, tace, tace, tak, tabe, or tBDD.
- 5. $\overline{\text{SEM}} = \text{VIH}.$
- 6. \overline{CE} = L occurs when \overline{CE}_0 = VIL and CE1 = VIH. \overline{CE} = H when \overline{CE}_0 = VIH and/or CE1 = VIL.

Timing of Power-Up Power-Down



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Timing Waveform of Write Cycle No. 1, R/W Controlled Timing^(1,5,8)



Timing Waveform of Write Cycle No. 2, CE Controlled Timing^(1,5,8)



- 1. R/\overline{W} or \overline{CE} or \overline{UB} or \overline{LB} = VIH during all address transitions.
- 2. A write occurs during the overlap (tew or twp) of a TE = VIL and a R/W = VIL for memory array writing cycle.
- 3. two is measured from the earlier of \overline{CE} or $\overline{R/W}$ (or \overline{SEM} or $\overline{R/W}$) going HIGH to the end of write cycle.
- 4. During this period, the I/O pins are in the output state and input signals must not be applied.
- 5. If the CE or SEM = VIL transition occurs simultaneously with or after the R/W = VIL transition, the outputs remain in the High-impedance state.
- 6. Timing depends on which enable signal is asserted last, \overline{CE} or R/\overline{W} .
- 7. This parameter is guaranteed by device characterization, but is not production tested. Transition is measured 0mV from steady state with the Output Test Load (Figure 1).
- 8. If $\overline{OE} = V_{IL}$ during R/W controlled write cycle, the write pulse width must be the larger of twp or (twz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If $\overline{OE} = V_{IH}$ during an R/W controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified twp.
- 9. To access RAM, \overline{CE} = VIL and \overline{SEM} = VIH. To access semaphore, \overline{CE} = VIH and \overline{SEM} = VIL. tew must be met for either condition. \overline{CE} = VIL when $\overline{CE_0}$ = VIL and \overline

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Industrial and Commercial Temperature Ranges

RapidWrite Mode Write Cycle

Unlike other vendors' Asynchronous Random Access Memories, the IDT70T633/1 is capable of performing multiple back-to-back write operations without having to pulse the R/ \overline{W} , \overline{CE} , or \overline{BE} n signals high during address transitions. This RapidWrite Mode functionality allows the system designer to achieve optimum back-to-back write cycle performance without the difficult task of generating narrow reset pulses every cycle, simplifying system design and reducing time to market.

During this new RapidWrite Mode, the end of the write cycle is now defined by the ending address transition, instead of the R/\overline{W} or \overline{CE} or \overline{BEn} transition to the inactive state. R/\overline{W} , \overline{CE} , and \overline{BEn} can be held active throughout the address transition between write cycles.

Care must be taken to still meet the Write Cycle time (twc), the time in which the Address inputs must be stable. Input data setup and hold times (tow and toH) will now be referenced to the ending address transition. In this RapidWrite Mode the I/O will remain in the Input mode for the duration of the operations due to R/W being held low. All standard Write Cycle specifications must be adhered to. However, tas and twR are only applicable when switching between read and write operations. Also, there are two additional conditions on the Address Inputs that must also be met to ensure correct address controlled writes. These specifications, the Allowable Address Skew (taas) and the Address Rise/Fall time (taRF), must be met to use the RapidWrite Mode. If these conditions are not met there is the potential for inadvertent write operations at random intermediate locations as the device transitions between the desired write addresses.





- 1. $\overline{OE} = V_{IL}$ for this timing waveform as shown. \overline{OE} may equal V_{IH} with same write functionality; I/O would then always be in High-Z state.
- 2. A write occurs during the overlap (tew or twp) of a $\overline{CE} = V_{IL}$, $\overline{BEn} = V_{IL}$, and a $R\overline{W} = V_{IL}$ for memory array writing cycle. The last transition LOW of \overline{CE} , \overline{BEn} , and $R\overline{W}$ initiates the write sequence. The first transition HIGH of \overline{CE} , \overline{BEn} , and $R\overline{W}$ terminates the write sequence.
- 3. If the CE or SEM = VIL transition occurs simultaneously with or after the R/W = VIL transition, the outputs remain in the High-impedance state.
- 4. The timing represented in this cycle can be repeated multiple times to execute sequential RapidWrite Mode writes.
- 5. This parameter is guaranteed by device characterization, but is not production tested. Transition is measured 0mV from steady state with the Output Test Load (Figure 1).
- 6. To access RAM, CE = VIL and SEM = VIH. To access semaphore, CE = VIH and SEM = VIL. tew must be met for either condition. CE = VIL when CE0 = VIL and CE1 = VIL. CE = VIH when CE0 = VIL and CE1 = VIL.

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AC Electrical Characteristics over the Operating Temperature Range and Supply Voltage Range for RapidWrite Mode Write Cycle⁽¹⁾

Symbol	Parameter	Min	Max	Unit
taas	Allowable Address Skew for RapidWrite Mode		1	ns
tarf	Address Rise/Fall Time for RapidWrite Mode	1.5		V/ns
				5670 tbl 14

NOTE:

1. Timing applies to all speed grades when utilizing the RapidWrite Mode Write Cycle.

Timing Waveform of Address Inputs for RapidWrite Mode Write Cycle



NOTE: 1. A17 for IDT70T631. 5670 drw 09

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Timing Waveform of Semaphore Read after Write Timing, Either Side⁽¹⁾



NOTES:

- 1. CE₀ = VIH and CE₁ = VIL are required for the duration of both the write cycle and the read cycle waveforms shown above. Refer to Truth Table II for details and for appropriate UB/LB controls.
- 2. "DATAOUT VALID" represents all I/O's (I/Oo I/O17) equal to the semaphore value.

Timing Waveform of Semaphore Write Contention^(1,3,4)



- 1. DOR = DOL = VIL, \overline{CE} OL = \overline{CE} OR = VIH; CE1L = CE1R = VIL. Refer also to Truth Table II for appropriate $\overline{UB}/\overline{LB}$ controls.
- 2. All timing is the same for left and right ports. Port "A" may be either left or right port. "B" is the opposite from port "A".
- 3. This parameter is measured from R/W "A" or SEM "A" going HIGH to R/W "B" or SEM "B" going HIGH.
- 4. If tsps is not satisfied, the semaphore will fall positively to one side or the other, but there is no guarantee which side will be granted the semaphore flag.

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AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range

Complete	Describer	Co	70T633/1S10 Com'l & Ind ⁽⁶⁾		70T633/1S12 Com'l & Ind		70T633/1S15 Com'l Only	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
BUSY TIMIN	G (M/S=Vih)		-					-
tBAA	BUSY Access Time from Address Match		10		12		15	ns
tBDA	BUSY Disable Time from Address Not Matched	_	10		12		15	ns
t BAC	BUSY Access Time from Chip Enable Low		10		12	_	15	ns
tBDC	BUSY Disable Time from Chip Enable High		10	_	12	_	15	ns
taps	Arbitration Priority Set-up Time ⁽²⁾	2.5		2.5		2.5	—	ns
tBDD	BUSY Disable to Valid Data ⁽³⁾	_	10		12	_	15	ns
twн	Write Hold After BUSY ⁽⁵⁾	7		9		12	_	ns
BUSY TIMIN	G (M/S=VIL)		-					-
twв	BUSY Input to Write ⁽⁴⁾	0	_	0		0	—	ns
twн	Write Hold After BUSY ⁽⁵⁾	7	_	9		12	—	ns
PORT-TO-PC	RT DELAY TIMING	•						
twdd	Write Pulse to Data Delay ⁽¹⁾		14		16		20	ns
todd	Write Data Valid to Read Data Delay ⁽¹⁾		14		16		20	ns

NOTES:

5670 tbl 15

1. Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Write with Port-to-Port Read and $\overline{\text{BUSY}}$ (M/ $\overline{\text{S}}$ = V_H)".

2. To ensure that the earlier of the two ports wins.

3. tbdb is a calculated parameter and is the greater of the Max. spec, twdb - twp (actual), or tbdb - tbw (actual).

4. To ensure that the write cycle is inhibited on port "B" during contention on port "A".

5. To ensure that a write cycle is completed on port "B" after contention on port "A".

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range^(1,2,3)

Cumhal	Descriptor	70T633/1S10 Com'l & Ind		70T6331S12 Com'l & Ind		70T633/1S15 Com'l Only		
Symbol	Parameter	Min.	Мах.	Min.	Мах.	Min.	Мах.	
SLEEP MODE TIMING (ZZx=VIH)								
tzzs	Sleep Mode Set Time	10		12	-	15		
tzzr	Sleep Mode Reset Time	10		12	-	15		
tzzpd	Sleep Mode Power Down Time ⁽⁴⁾	10		12		15		
tzzpu	Sleep Mode Power Up Time ⁽⁴⁾		0		0		0	

5670 tbl 15a

NOTES:

1. Timing is the same for both ports.

2. The sleep mode pin shuts off all dynamic inputs, except JTAG inputs, when asserted. OPTx, INTx, M/S and the sleep mode pins themselves (ZZx) are not affected during sleep mode. It is recommended that boundary scan not be operated during sleep mode.

3. These values are valid regardless of the power supply level selected for I/O and control signals (3.3V/2.5V). See page 5 for details.

4. This parameter is guaranteed by device characterization, but is not production tested.

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Timing Waveform of Write with Port-to-Port Read and **BUSY** $(M/S = VIH)^{(2,4,5)}$



NOTES:

- 1. To ensure that the earlier of the two ports wins. taps is ignored for $M/\overline{S} = VIL$ (SLAVE).
- 2. \overline{CE} OL = \overline{CE} OR = VIL; CE1L = CE1R = VIH.
- 3. $\overline{OE} = V_{IL}$ for the reading port.
- 4. If $M/\overline{S} = V_{IL}$ (slave), \overline{BUSY} is an input. Then for this example $\overline{BUSY}^*A^* = V_{IH}$ and \overline{BUSY}^*B^* input is shown above.
- 5. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

Timing Waveform of Write with **BUSY** (M/S = VIL)



- 1. twh must be met for both $\overline{\text{BUSY}}$ input (SLAVE) and output (MASTER).
- 2. BUSY is asserted on port "B" blocking R/W"B", until BUSY"B" goes HIGH.
- 3. two only applies to the slave mode.

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Waveform of **BUSY** Arbitration Controlled by \overline{CE} Timing (M/ \overline{S} = VIH)⁽¹⁾



Waveform of **BUSY** Arbitration Cycle Controlled by Address Match Timing $(M/S = VIH)^{(1,3,4)}$



NOTES:

1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

2. If tAPS is not satisfied, the BUSY signal will be asserted on one side or another but there is no guarantee on which side BUSY will be asserted.

3. $\overline{CE}x = V_{IL}$ when $\overline{CE}_{0x} = V_{IL}$ and $\overline{CE}_{1x} = V_{IH}$. $\overline{CE}_{x} = V_{IH}$ when $\overline{CE}_{0x} = V_{IH}$ and/or $CE_{1x} = V_{IL}$.

4. $\overline{CE}_{0x} = \overline{OE}_x = \overline{LB}_x = \overline{UB}_x = V_{IL}$. $CE_{1x} = V_{IH}$.

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range^(1,2)

		70T633/1S10 Com'l & Ind Min. Max.		70T633/1S12 Com'l & Ind		70T633/1S15 Com'l Only		
Symbol	Parameter			Min.	Мах.	Min.	Мах.	Unit
INTERRUPT T	TIMING							
tas	Address Set-up Time	0		0		0		ns
twR	Write Recovery Time	0		0		0		ns
tiNS	Interrupt Set Time	_	10		12		15	ns
tinr	Interrupt Reset Time	—	10	_	12		15	ns
							•	5670 tbl 16

NOTES:

1. Timing is the same for both ports.

2. These values are valid regardless of the power supply level selected for I/O and control signals (3.3V/2.5V). See page 5 for details.



NOTES:

1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

2. Refer to Interrupt Truth Table.

3. $\overline{CE}x = V_{IL}$ means $\overline{CE}_{0x} = V_{IL}$ and $CE_{1x} = V_{IH}$. $\overline{CE}x = V_{IH}$ means $\overline{CE}_{0x} = V_{IH}$ and/or $CE_{1x} = V_{IL}$.

4. Timing depends on which enable signal (\overline{CE} or R/\overline{W}) is asserted last.

5. Timing depends on which enable signal $(\overline{CE} \text{ or } R/\overline{W})$ is de-asserted first.

	Left Port						Right Por	t		
R/₩L	CEL	ŌĒL	A18L-A0L ⁽⁵⁾	ĪNTL	R/WR	CER	OE R	A18R-A0R ⁽⁵⁾	ĪNTR	Function
L	L	Х	7FFFF	Х	Х	Х	Х	Х	L ⁽²⁾	Set Right INTR Flag
Х	Х	Х	Х	Х	Х	L	L	7FFFF	H ⁽³⁾	Reset Right INTR Flag
Х	Х	Х	Х	L ⁽³⁾	L	L	Х	7FFFE	Х	Set Left INTL Flag
Х	L	L	7FFFE	H ⁽²⁾	Х	Х	Х	Х	Х	Reset Left INTL Flag

Truth Table III — Interrupt Flag^(1,4)

NOTES:

1. Assumes $\overline{\text{BUSY}}_{L} = \overline{\text{BUSY}}_{R} = V_{IH}$. $\overline{\text{CE}}_{x} = L$ means $\overline{\text{CE}}_{0x} = V_{IL}$ and $CE_{1x} = V_{IH}$.

2. If $\overline{\text{BUSY}}_{L} = V_{IL}$, then no change.

3. If $\overline{\text{BUSY}}_{R} = \text{VIL}$, then no change.

4. \overline{INT}_{L} and \overline{INT}_{R} must be initialized at power-up.

5. A18x is a NC for IDT70T631. Therefore, Interrupt Addresses are 3FFFF and 3FFFE.

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Truth Table IV — Address **BUSY** Arbitration

	In	puts	Out	puts	
CEL ⁽⁵⁾	CER ⁽⁵⁾	A0L-A18L ⁽⁴⁾ A0R-A18R	BUSYL ⁽¹⁾	BUSY _R ⁽¹⁾	Function
Х	Х	NO MATCH	Н	Н	Normal
Н	Х	MATCH	Н	Н	Normal
Х	Н	MATCH	Н	Н	Normal
L	L	MATCH	(2)	(2)	Write Inhibit ⁽³⁾

NOTES:

5670 tbl 18

1. Pins BUSYL and BUSYR are both outputs when the part is configured as a master. Both are inputs when configured as a slave. BUSY outputs on the IDT70T633/1 are push-pull, not open drain outputs. On slaves the BUSY input internally inhibits writes.

- 2. "L" if the inputs to the opposite port were stable prior to the address and enable inputs of this port. "H" if the inputs to the opposite port became stable after the address and enable inputs of this port. If tAPS is not met, either BUSYL or BUSYR = LOW will result. BUSYL and BUSYR outputs can not be LOW simultaneously.
- 3. Writes to the left port are internally ignored when BUSYL outputs are driving LOW regardless of actual logic level on the pin. Writes to the right port are internally ignored when BUSYR outputs are driving LOW regardless of actual logic level on the pin.
- 4. A18 is a NC for IDT70T631. Address comparison will be for Ao A17.
- 5. $\overline{CE}x = L$ means $\overline{CE}ox = V_{IL}$ and $CE_{1X} = V_{IH}$. $\overline{CE}x = H$ means $\overline{CE}ox = V_{IH}$ and/or $CE_{1X} = V_{IL}$.

Truth Table V — Example of Semaphore Procurement Sequence^(1,2,3)

Functions	Do - D17 Left	Do - D17 Right	Status
No Action	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Right Port Writes "0" to Semaphore	0	1	No change. Right side has no write access to semaphore
Left Port Writes "1" to Semaphore	1	0	Right port obtains semaphore token
Left Port Writes "0" to Semaphore	1	0	No change. Left port has no write access to semaphore
Right Port Writes "1" to Semaphore	0	1	Left port obtains semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free
Right Port Writes "0" to Semaphore	1	0	Right port has semaphore token
Right Port Writes "1" to Semaphore	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free

NOTES:

1. This table denotes a sequence of events for only one of the eight semaphores on the IDT70T633/1.

2. There are eight semaphore flags written to via I/Oo and read from all I/O's (I/Oo-I/O17). These eight semaphores are addressed by Ao - A2.

3. $\overline{CE}_0 = V_{IH}$, $\widetilde{CE}_1 = \overline{SEM} = V_{IL}$ to access the semaphores. Refer to the Semaphore Read/Write Control Truth Table.

Functional Description

The IDT70T633/1 provides two ports with separate control, address and I/O pins that permit independent access for reads or writes to any location in memory. The IDT70T633/1 has an automatic power down feature controlled by \overline{CE} . The \overline{CE} and CE_1 control the on-chip power down circuitry that permits the respective port to go into a standby mode when not selected ($\overline{CE} = HIGH$). When a port is enabled, access to the entire memory array is permitted.

Interrupts

If the user chooses the interrupt function, a memory location (mail box or message center) is assigned to each port. The left port interrupt flag ($\overline{INT}L$) is asserted when the right port writes to memory location 7FFFE (HEX), where a write is defined as $\overline{CE}R = R/\overline{W}R = VIL$ per the Truth Table. The left port clears the interrupt through access of address location 7FFFE when $\overline{CE}L = \overline{OE}L = VIL$, R/\overline{W} is a "don't care". Likewise, the right port interrupt flag ($\overline{INT}R$) is asserted when the left port writes to memory location 7FFFF (HEX) and to clear the interrupt flag ($\overline{INT}R$), the right port must read the memory location 7FFFF. The message (18 bits) at 7FFFE or 7FFFF (3FFFF or 3FFFE for IDT70T631) is user-defined since it is an addressable SRAM location. If the interrupt function is not used, address locations 7FFFE and 7FFFF are not used as mail boxes, but as part of the random access memory. Refer to Truth Table III for the interrupt operation.

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BusyLogic

Busy Logic provides a hardware indication that both ports of the RAM have accessed the same location at the same time. It also allows one of the two accesses to proceed and signals the other side that the RAM is "Busy". The $\overline{\text{BUSY}}$ pin can then be used to stall the access until the operation on the other side is completed. If a write operation has been attempted from the side that receives a $\overline{\text{BUSY}}$ indication, the write signal is gated internally to prevent the write from proceeding.

The use of BUSY logic is not required or desirable for all applications. In some cases it may be useful to logically OR the BUSY outputs together and use any BUSY indication as an interrupt source to flag the event of an illegal or illogical operation. If the write inhibit function of BUSY logic is not desirable, the BUSY logic can be disabled by placing the part in slave mode with the M/S pin. Once in slave mode the BUSY pin operates solely as a write inhibit input pin. Normal operation can be programmed by tying the BUSY pins HIGH. If desired, unintended write operations can be prevented to a port by tying the BUSY pin for that port LOW.

The BUSY outputs on the IDT70T633/1 RAM in master mode, are push-pull type outputs and do not require pull up resistors to operate. If these RAMs are being expanded in depth, then the BUSY indication for the resulting array requires the use of an external AND gate.



Figure 3. Busy and chip enable routing for both width and depth expansion with IDT70T633/1 Dual-Port RAMs.

Width Expansion with Busy Logic Master/Slave Arrays

When expanding an IDT70T633/1 RAM array in width while using $\overline{\text{BUSY}}$ logic, one master part is used to decide which side of the RAMs array will receive a $\overline{\text{BUSY}}$ indication, and to output that indication. Any number of slaves to be addressed in the same address range as the master use the $\overline{\text{BUSY}}$ signal as a write inhibit signal. Thus on the IDT70T633/1 RAM the $\overline{\text{BUSY}}$ pin is an output if the part is used as a master (M/S pin = VIH), and the $\overline{\text{BUSY}}$ pin is an input if the part used as a slave (M/S pin = VIL) as shown in Figure 3.

If two or more master parts were used when expanding in width, a split decision could result with one master indicating BUSY on one side of the array and another master indicating BUSY on one other side of the array. This would inhibit the write operations from one port for part of a word and inhibit the write operations from the other port for the other part of the word.

The BUSY arbitration on a master is based on the chip enable and

address signals only. It ignores whether an access is a read or write. In a master/slave array, both address and chip enable must be valid long enough for a $\overline{\text{BUSY}}$ flag to be output from the master before the actual write pulse can be initiated with the $R\overline{W}$ signal. Failure to observe this timing can result in a glitched internal write inhibit signal and corrupted data in the slave.

Semaphores

The IDT70T633/1 is an extremely fast Dual-Port 512/256K x 18 CMOS Static RAM with an additional 8 address locations dedicated to binary semaphore flags. These flags allow either processor on the left or right side of the Dual-Port RAM to claim a privilege over the other processor for functions defined by the system designer's software. As an example, the semaphore can be used by one processor to inhibit the other from accessing a portion of the Dual-Port RAM or any other shared resource.

The Dual-Port RAM features a fast access time, with both ports being completely independent of each other. This means that the activity on the left port in no way slows the access time of the right port. Both ports are identical in function to standard CMOS Static RAM and can be read from or written to at the same time with the only possible conflict arising from the simultaneous writing of, or a simultaneous READ/WRITE of, a non-semaphore location. Semaphores are protected against such ambiguous situations and may be used by the system program to avoid any conflicts in the non-semaphore portion of the Dual-Port RAM. These devices have an automatic power-down feature controlled by CEo and CE1, the Dual-Port RAM chip enables, and SEM, the semaphore enable. The CE0, CE1, and SEM pins control on-chip power down circuitry that permits the respective port to go into standby mode when not selected.

Systems which can best use the IDT70T633/1 contain multiple processors or controllers and are typically very high-speed systems which are software controlled or software intensive. These systems can benefit from a performance increase offered by the hardware semaphores of the IDT70T633/1, which provide a lockout mechanism without requiring complex programming.

Software handshaking between processors offers the maximum in system flexibility by permitting shared resources to be allocated in varying configurations. The IDT70T633/1 does not use its semaphore flags to control any resources through hardware, thus allowing the system designer total flexibility in system architecture.

An advantage of using semaphores rather than the more common methods of hardware arbitration is that wait states are never incurred in either processor. This can prove to be a major advantage in very high-speed systems.

How the Semaphore Flags Work

The semaphore logic is a set of eight latches which are independent of the Dual-Port RAM. These latches can be used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphores provide a hardware assist for a use assignment method called "Token Passing Allocation." In this method, the state of a semaphore latch is used as a token indicating that a shared resource is in use. If the left processor wants to use this resource, it requests the token by setting the latch. This processor then

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verifies its success in setting the latch by reading it. If it was successful, it proceeds to assume control over the shared resource. If it was not successful in setting the latch, it determines that the right side processor has set the latch first, has the token and is using the shared resource. The left processor can then either repeatedly request that semaphore's status or remove its request for that semaphore to perform another task and occasionally attempt again to gain control of the token via the set and test sequence. Once the right side has relinquished the token, the left side should succeed in gaining control.

The semaphore flags are active LOW. A token is requested by writing a zero into a semaphore latch and is released when the same side writes a one to that latch.

The eight semaphore flags reside within the IDT70T633/1 in a separate memory space from the Dual-Port RAM array. This address space is accessed by placing a low input on the \overline{SEM} pin (which acts as a chip select for the semaphore flags) and using the other control pins (Address, \overline{CE}_0 , CE1, R/W and \overline{LB}/UB) as they would be used in accessing a standard Static RAM. Each of the flags has a unique address which can be accessed by either side through address pins Ao – A2. When accessing the semaphores, none of the other address pins has any effect.

When writing to a semaphore, only data pin Do is used. If a low level is written into an unused semaphore location, that flag will be set to a zero on that side and a one on the other side (see Truth Table V). That semaphore can now only be modified by the side showing the zero. When a one is written into the same location from the same side, the flag will be set to a one for both sides (unless a semaphore request from the other side is pending) and then can be written to by both sides. The fact that the side which is able to write a zero into a semaphore subsequently locks out writes from the other side is what makes semaphore flags useful in interprocessor communications. (A thorough discussion on the use of this feature follows shortly.) A zero written into the same location from the other side will be stored in the semaphore request latch for that side until the semaphore is freed by the first side.

When a semaphore flag is read, its value is spread into all data bits so that a flag that is a one reads as a one in all data bits and a flag containing a zero reads as all zeros for a semaphore read, the SEM, BEn, and OE signals need to be active. (Please refer to Truth Table II). Furthermore, the read value is latched into one side's output register when that side's semaphore select (SEM, BEn) and output enable (OE) signals go active. This serves to disallow the semaphore from changing state in the middle of a read cycle due to a write cycle from the other side.

A sequence WRITE/READ must be used by the semaphore in order to guarantee that no system level contention will occur. A processor requests access to shared resources by attempting to write a zero into a semaphore location. If the semaphore is already in use, the semaphore request latch will contain a zero, yet the semaphore flag will appear as one, a fact which the processor will verify by the subsequent read (see Table V). As an example, assume a processor writes a zero to the left port at a free semaphore location. On a subsequent read, the processor will verify that it has written successfully to that location and will assume control over the resource in question. Meanwhile, if a processor on the right side attempts to write a zero to the same semaphore flag it will fail, as will be verified by the fact that a one will be read from that semaphore on the right side during subsequent read. Had a sequence of READ/WRITE been used instead, system contention problems could have occurred during the gap between the read and write cycles.

It is important to note that a failed semaphore request must be followed by either repeated reads or by writing a one into the same location. The reason for this is easily understood by looking at the simple logic diagram of the semaphore flag in Figure 4. Two semaphore request latches feed into a semaphore flag. Whichever latch is first to present a zero to the semaphore flag will force its side of the semaphore flag LOW and the opposite side HIGH. This condition will continue until a one is written to the same semaphore request latch.



If the opposite side semaphore request latch has been written to zero in the meantime, the semaphore flag will flip over to the other side as soon as a one is written into the first request latch. The opposite side flag will now stay LOW until its semaphore request latch is written to a one. From this it is easy to understand that, if a semaphore is requested and the processor which requested it no longer needs the resource, the entire system can hang up until a one is written into that semaphore request latch.

The critical case of semaphore timing is when both sides request a single token by attempting to write a zero into it at the same time. The semaphore logic is specially designed to resolve this problem. If simultaneous requests are made, the logic guarantees that only one side receives the token. If one side is earlier than the other in making the request, the first side to make the request will receive the token. If both requests arrive at the same time, the assignment will be arbitrarily made to one port or the other.

One caution that should be noted when using semaphores is that semaphores alone do not guarantee that access to a resource is secure. As with any powerful programming technique, if semaphores are misused or misinterpreted, a software error can easily happen.

Initialization of the semaphores is not automatic and must be handled via the initialization program at power-up. Since any semaphore request flag which contains a zero must be reset to a one, all semaphores on both sides should have a one written into them at initialization from both sides to assure that they will be free when needed.

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NOTES: 1. CE1 = VIH 2. All timing is same for Left and Right ports.

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Sleep Mode

The IDT70T633/1 is equipped with an optional sleep or low power mode on both ports. The sleep mode pin on both ports is active high. During normal operation, the ZZ pin is pulled low. When ZZ is pulled high, the port will enter sleep mode where it will have the lowest possible power consumption. The sleep mode timing diagram demonstrates the modes of operation: Normal Operation, No Read/Write Allowed and Sleep Mode. For a period of time prior to sleep mode and after recovering from sleep

mode (tzzs and tzzR), new reads or writes are not allowed. If a write or read operation occurs during these periods, the memory array may be corrupted. Validity of data out from the RAM cannot be guaranteed immediately after ZZ is asserted (prior to being in sleep).

During sleep mode the RAM automatically deselects itself and disconnects its internal buffer. All outputs will remain in high-Z state while in sleep mode. All inputs are allowed to toggle, but the RAM will not be selected and will not perform any reads or writes.

JTAG Timing Specifications



NOTES:

- 1. Device inputs = All device inputs except TDI, TMS, and TRST.
- 2. Device outputs = All device outputs except TDO.

JTAG AC Electrical Characteristics^(1,2,3,4,5)

			70T633/1	
Symbol	Parameter	Min.	Max.	Units
ticyc	JTAG Clock Input Period	100		ns
тсн	JTAG Clock HIGH	40		ns
tJCL	JTAG Clock Low	40		ns
UR	JTAG Clock Rise Time		3(1)	ns
ĹΓ	JTAG Clock Fall Time		3(1)	ns
U RST	JTAG Reset	50		ns
U RSR	JTAG Reset Recovery	50		ns
ticd	JTAG Data Output		25	ns
tudc	JTAG Data Output Hold	0		ns
tıs	JTAG Setup	15		ns
tн	JTAG Hold	15		ns
				5670 tbl 20

NOTES:

- 1. Guaranteed by design.
- 2. 30pF loading on external output signals.
- 3. Refer to AC Electrical Test Conditions stated earlier in this document.
- JTAG operations occur at one speed (10MHz). The base device may run at any speed specified in this datasheet.
- 5. JTAG cannot be tested in sleep mode.

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Identification Register Definitions

Instruction Field	Value	Description
Revision Number (31:28)	0x0	Reserved for version number
IDT Device ID (27:12)	0x33B ⁽¹⁾	Defines IDT part number 70T633
IDT JEDEC ID (11:1)	0x33	Allows unique identification of device vendor as IDT
ID Register Indicator Bit (Bit 0)	1	Indicates the presence of an ID register

NOTE:

1. Device ID for IDT70T631 is 0x33C.

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5670 tbl 23

Scan Register Sizes

Register Name	Bit Size
Instruction (IR)	4
Bypass (BYR)	1
Identification (IDR)	32
Boundary Scan (BSR)	Note (3)

5670 tbl 22

System Interface Parameters

Instruction	Code	Description	
EXTEST	0000	Forces contents of the boundary scan cells onto the device outputs ⁽¹⁾ . Places the boundary scan register (BSR) between TDI and TDO.	
BYPASS	1111	Places the bypass register (BYR) between TDI and TDO.	
IDCODE	0010	Loads the ID register (IDR) with the vendor ID code and places the register between TDI and TDO.	
HIGHZ	0100	Places the bypass register (BYR) between TDI and TDO. Forces all device output drivers to a High-Z state.	
CLAMP	0011	Uses BYR. Forces contents of the boundary scan cells onto the device outputs. Places the bypass register (BYR) between TDI and TDO.	
SAMPLE/PRELOAD	0001	Places the boundary scan register (BSR) between TDI and TDO. SAMPLE allows data from device inputs ⁽²⁾ and outputs ⁽¹⁾ to be capture in the boundary scan cells and shifted serially through TDO. PRELOA allows data to be input serially into the boundary scan cells via the T	
RESERVED	All other codes	Several combinations are reserved. Do not use codes other than those identified above.	

NOTES:

1. Device outputs = All device outputs except TDO.

2. Device inputs = All device inputs except TDI, TMS, and $\overline{\text{TRST}}$.

3. The Boundary Scan Descriptive Language (BSDL) file for this device is available on the IDT website (www.idt.com), or by contacting your local IDT sales representative.

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Ordering Information



Tape and Reel Commercial (0°C to +70°C) Industrial (-40°C to +85°C) Green 256-ball BGA (BC256, BCG256) 208-ball fpBGA (BF208, BFG208) Commercial & Industrial Commercial & Industrial Commercial & Industrial Commercial Only

Standard Power

70T633 9Mbit (512K x 18) 2.5V Asynchronous Dual-Port RAM 70T631 4Mbit (256K x 18) 2.5V Asynchronous Dual-Port RAM 5670 drv 24

NOTES:

1. Green parts available. For specific speeds and packages contact your local sales office.

Orderable Part Information

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
10	70T633S10BC	BC256	CABGA	С
	70T633S10BC8	BC256	CABGA	С
	70T633S10BCGI	BCG256	CABGA	I
	70T633S10BCI	BC256	CABGA	I
	70T633S10BCl8	BC256	CABGA	I
	70T633S10BF	BF208	CABGA	С
	70T633S10BF8	BF208	CABGA	С
	70T633S10BFG	BFG208	CABGA	С
	70T633S10BFG8	BFG208	CABGA	С
	70T633S10BFGI	BFG208	CABGA	I
	70T633S10BFGI8	BFG208	CABGA	I
	70T633S10BFI	BF208	CABGA	I
	70T633S10BFI8	BF208	CABGA	I
12	70T633S12BC	BC256	CABGA	С
	70T633S12BC8	BC256	CABGA	С
	70T633S12BCI	BC256	CABGA	I
	70T633S12BCl8	BC256	CABGA	I
	70T633S12BF	BF208	CABGA	С
	70T633S12BF8	BF208	CABGA	С
	70T633S12BFGI	BFG208	CABGA	I
	70T633S12BFGl8	BFG208	CABGA	I
	70T633S12BFI	BF208	CABGA	I
	70T633S12BFI8	BF208	CABGA	I
15	70T633S15BC	BC256	CABGA	С
	70T633S15BC8	BC256	CABGA	С
	70T633S15BF	BF208	CABGA	С
	70T633S15BF8	BF208	CABGA	С

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
10	70T631S10BC	BC256	CABGA	С
	70T631S10BC8	BC256	CABGA	С
	70T631S10BCI	BC256	CABGA	I
	70T631S10BCI8	BC256	CABGA	I
	70T631S10BF	BF208	CABGA	С
	70T631S10BF8	BF208	CABGA	С
	70T631S10BFI	BF208	CABGA	I
	70T631S10BFI8	BF208	CABGA	I
12	70T631S12BC	BC256	CABGA	С
	70T631S12BC8	BC256	CABGA	С
	70T631S12BCI	BC256	CABGA	I
	70T631S12BCI8	BC256	CABGA	I
	70T631S12BF	BF208	CABGA	С
	70T631S12BF8	BF208	CABGA	С
	70T631S12BFI	BF208	CABGA	I
	70T631S12BFI8	BF208	CABGA	I
15	70T631S15BC	BC256	CABGA	С
	70T631S15BC8	BC256	CABGA	С
	70T631S15BF	BF208	CABGA	С
	70T631S15BF8	BF208	CABGA	С

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Datasheet Document History:

04/25/03:		Initial Datasheet
10/01/03:	Page 9	Added 8ns speed DC power numbers to DC Electrical Characteristics Table
	Page 9	Updated DC power numbers for 10, 12 & 15ns speeds in the DC Electrical Characteristics Table
	Page 9,11,15,	Added footnote that indicates that 8ns speed is available in BF-208 and BC-256 packages only
	17&25	
	Page 10	Added Capacitance Derating Drawing
	Page 11,15 & 17	Added 8ns AC timing numbers to the AC Electrical Characteristics Tables
	Page 11	Added tsoe and tLzob to the AC Read Cycle Electrical Characteristics Table
	Page 12	Added tLZOB to the Waveform of Read Cycles Drawing
	Page 14	Added tsoe to Timing Waveform of Semaphore Read after Write Timing, Either Side Drawing
	Page 1& 25	Added 8ns speed grade and 10ns I-temp to features and to ordering information
	Page 1, 14 & 15	Added RapidWrite Mode Write Cycle text and waveforms
10/20/03:	Page 15	Corrected tare to 1.5V/ns Min.
04/21/04:		Removed Preliminary status from entire datasheet
01/05/06:	Page 1	Added green availability to features
	Page 27	Added green indicator to ordering information
07/25/08:	Page 9	Corrected a typo in the DC Chars table
01/19/09:	Page 27	Removed "IDT" from orderable part number
04/20/10:		Removed the DD 144-pin TQFP (DD-144) Thin Quad Flatpack per PDN: F-08-01
10/15/11:	Page 2,13	Corrected 70T651/9 to 70T633/1
	Page 26	Updated ordering information to include tube or tray and tape & reel.
06/18/12:	Page 1, 2, 8, 10,	Removed 8ns from datasheet to match pricebook.
	16,18,26	
11/27/17:		Product Discontinuation Notice - PDN# SP-17-02
		Last time buy expires June 15, 2018
08/30/19:	Page 3 & 4	Updated package codes BC-256 to BC256, BCG256 and BF-208 to BF208, BFG208
	Page 26	Added Orderable Part Information tables
	Page 26	PDN# SP-17-02 does not apply. No LEAD FINISH (SnPb) parts were EOL'd. The associated note
		has been removed.